



Code: 9D06106c

M.Tech II Semester Supplementary Examinations August/September 2018

**LOW POWER VLSI DESIGN**

(Electronics & Communication Engineering)

(For students admitted in 2013, 2014, 2015 & 2016 only)

Time: 3 hours

Max. Marks: 60

Answer any FIVE questions  
All questions carry equal marks

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- 1 Explain the limitations of low-voltage, low-power design w.r.t the following:
  - (a) Power supply voltage.
  - (b) Threshold voltage.
  - (c) Scaling.
  - (d) Interconnect wires.
- 2 (a) What are the considerations to be taken care while integrating BiCMOS process? Explain.  
(b) Discuss briefly the p-well CMOS process and Twin-well Bi-CMOS process.
- 3 Illustrate a  $0.2\ \mu\text{m}$  SOI BiCMOS process flow and then explain each step of it.
- 4 Explain in detail the current model of advanced MOSFET model.
- 5 Discuss the following basic driver configurations of BiCMOS logic circuit:
  - (a) The common-emitter.
  - (b) The gated diode.
  - (c) The emitter follower.
- 6 (a) Design ESD-free BiCMOS inverter and then explain the same.  
(b) Compare performance of ESD-free BiCMOS digital circuit with an optimized two-stage CMOS and the TS-FS-BiCMOS circuits.
- 7 (a) Explain the pipelining theme by taking a negative edge-triggered  $\text{C}^2\text{MOS}$  flip-flop.  
(b) Develop a dynamic negative-edge triggered flip-flop based on pass transistor logic and then explain the same.
- 8 Describe the following low power techniques for SRAM:
  - (a) Memory bank partitioning.
  - (b) Pulsed word line and reduce bitline swing.

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